

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [0877050021](#)
Status: **Active**
Description: 1.00mm (.039") Pitch DDR-II DIMM Socket, Vertical, Center Keys, 2.67mm (.105") Tail Length, Beige Latches, 0.38µm (15µ") Gold (Au) Plating, with Beveled Metal Pins, 240 Circuits, Lead-Free

Documents:

[3D Model](#) [Product Specification PS-87705-002 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA 1409726
UL E29179

General

Product Family Memory Module Sockets
Series [87705](#)
Comments Latches in Beige Color
Component Type Socket
JEDEC Outline MO-237
Product Name DDR2 DIMM

Physical

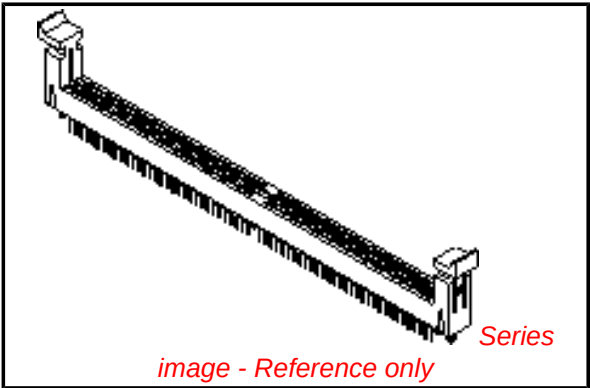
Circuits (Loaded) 240
Color - Resin Black, Natural
Durability (mating cycles max) 25
Entry Angle Vertical (Top Entry)
Flammability 94V-0
Keying to Mating Part Yes
Material - Metal Brass, Phosphor Bronze
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
PC Tail Length (in) 0.105 In
PC Tail Length (mm) 2.67 mm
PCB Retention Yes
PCB Thickness Recommended (in) 0.062 In
PCB Thickness Recommended (mm) 1.60 mm
Packaging Type Tray
Pitch - Mating Interface (in) 0.039 In
Pitch - Mating Interface (mm) 1.00 mm
Plating min: Mating (µin) 15.2
Plating min: Mating (µm) 0.38
Plating min: Termination (µin) 101.6
Plating min: Termination (µm) 2.54
Temperature Range - Operating -10°C to +85°C
Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact 0.5A
Voltage - Maximum 30V
Voltage Key 1.8V, Center

Solder Process Data

Duration at Max. Process Temperature (seconds) 5
Lead-free Process Capability SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature 1



EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
Not Reviewed
**Halogen-Free
Status**

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series
[87705Series](#)

Mates With
JEDEC standard 1.27mm modules

Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Product Specification	PS-87705-002
Sales Drawing	SD-87705-001

This document was generated on 05/27/2010

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10 9 8 7 6 5 4 3 2 1

NOTES:

1. MATERIALS

HOUSING - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0
COLOR: BLACK
EJECTOR - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0
COLOR: SEE TABLE
TERMINAL - COPPER ALLOY

2. PLATING - SEE TABLE IN SHEET 5 & 6.

3. CARD SLOT ACCEPTS 1.27±0.10 MM MODULE THICKNESS.
(MEASURED OVER P.C. PADS)

4. RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-237.

5. REFER TO PRODUCT SPEC. PS-87705-002 FOR PERFORMANCE
SPECIFICATIONS.

6. PRODUCT SHALL BE PACKED IN TRAY.

7. PRODUCT SHALL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.

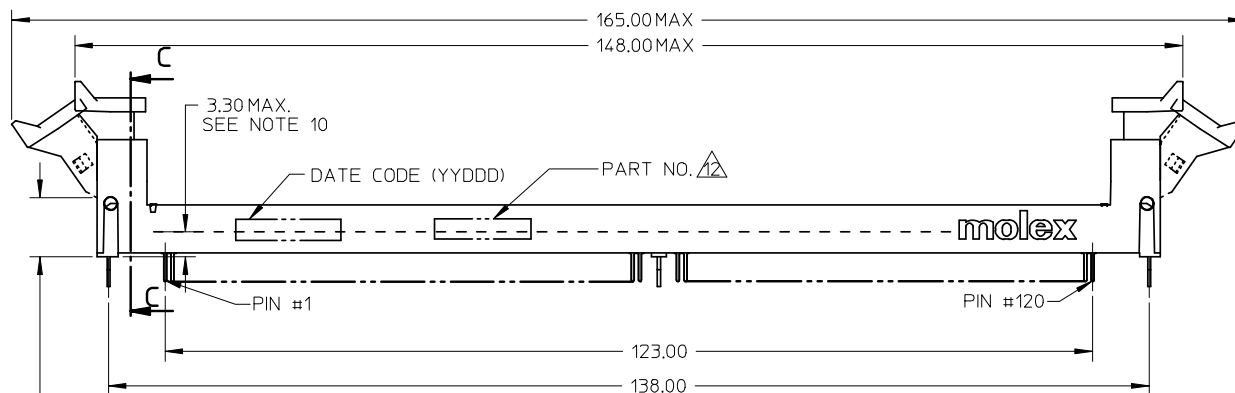
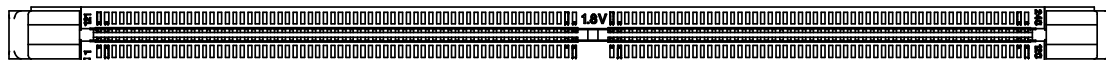
8. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS
MOUNTED ONTO THE PCB WHICH DOES NOT INCLUDE THE LATCH.

9. REFER TO CRITICAL JEDEC INFORMATION FOR SOCKET OUTLINE
PER SO-001.

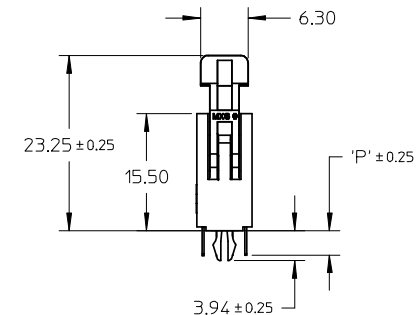
10. DIMM MODULE SEATING PLANE FROM TOP OF PCB.

11. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

△ PART NUMBER SHALL BE MARKED LEGIBLY AS 87705-****



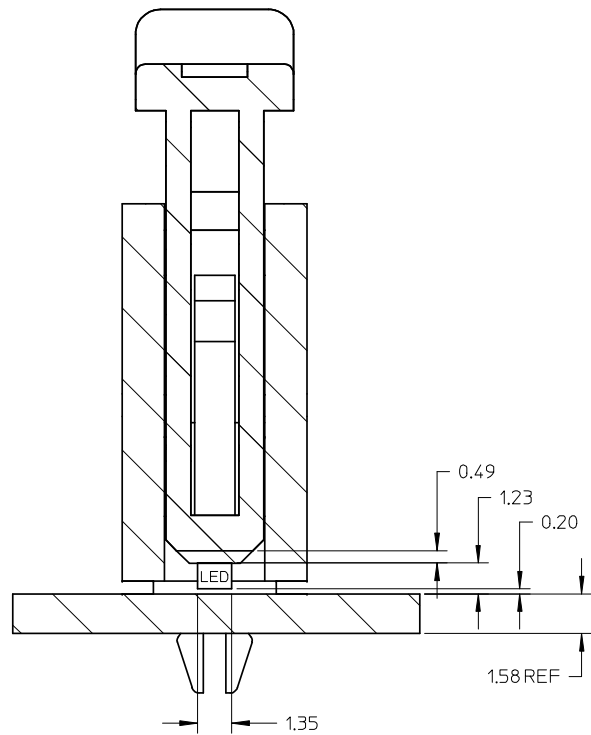
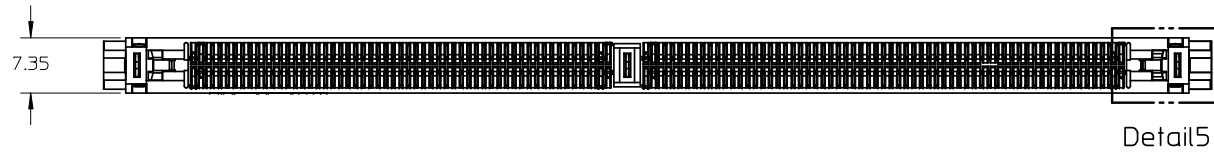
5.00 MIN
LATCH KEEP
OUT AREA



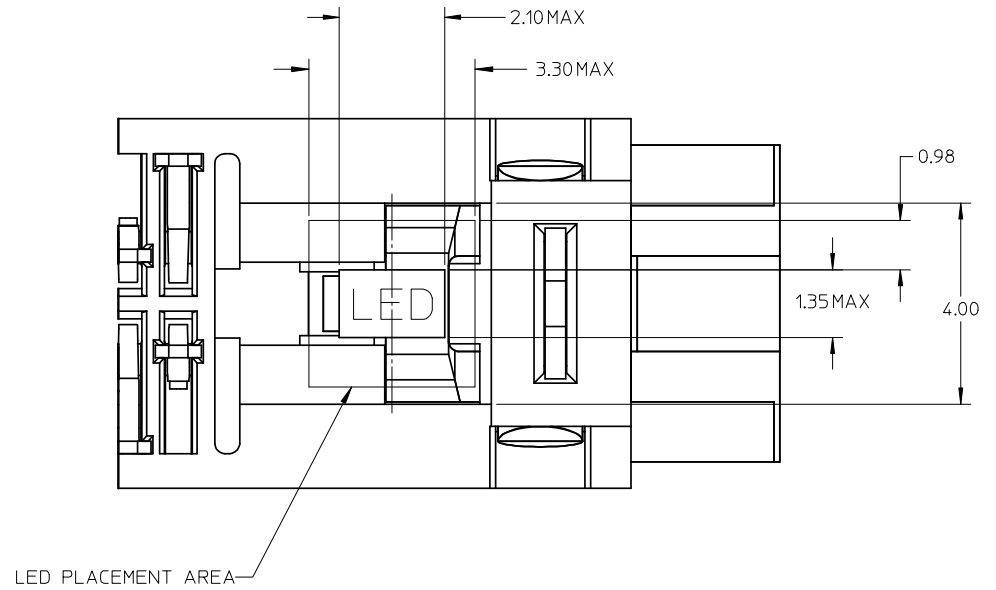
ADD NOTE @SHT4 C1 EC NO: S2008-1044 DRWN:CMTEO 2008/05/15 CHKD:CGTAN 2008/05/15 APPR:SHLENI 2008/05/15 REV			QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
					mm	INCH	DRAWN BY CGOH		DATE 2002/05/09	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS (FORKLOCK VERSION)		
				4 PLACES	± ---	± ---	CHECKED BY DSOH		DATE 2002/07/22			
				3 PLACES	± ---	± ---	APPROVED BY SKTOH		DATE 2002/07/23	MOLEX INCORPORATED DOCUMENT NO. SD-87705-001 SHEET NO. 1 OF 6		
2 PLACES	± 0.20	± ---	MATERIAL NO.									
1 PLACE	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE							
ANGULAR ± 5 °				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



SECTION C-C



Detail 5

ADD NOTE @SHT4 C1			DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
EC NO: S2008-1044					▽=0 ▽=0	mm		INCH		DRAWN BY	DATE	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)			
2008/05/15						4 PLACES	± ---	± ---	CGOH	2002/05/09					
DRWN:CMTEO						3 PLACES	± ---	± ---	CHECKED BY	DATE					
2008/05/15						2 PLACES	± 0.20	± ---	DSOH	2002/07/22					
CHKD:CGTAN						1 PLACE	± ---	± ---	APPROVED BY	DATE					
2008/05/15					ANGULAR ± 5 °			SKTOH	2002/07/23	molex		MOLEX INCORPORATED			
APPR:SHLENI					DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
								SEE TABLE		SD-87705-001		2 OF 6			
D1								SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
REV															

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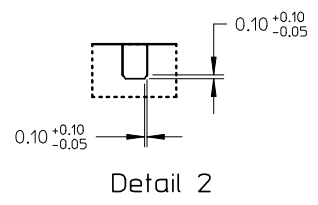
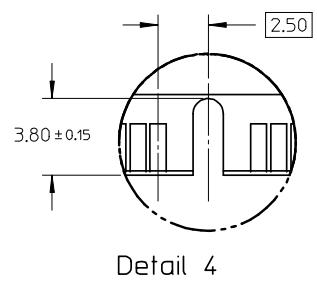
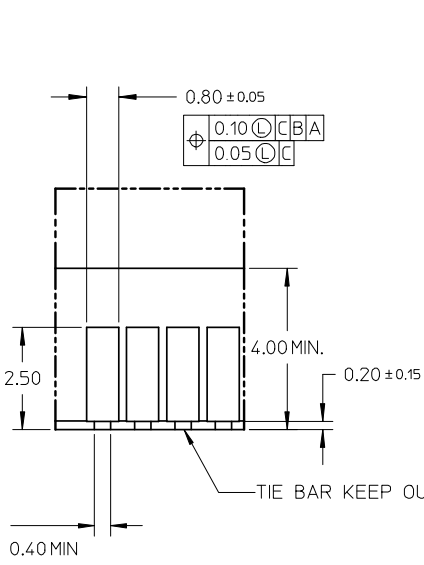
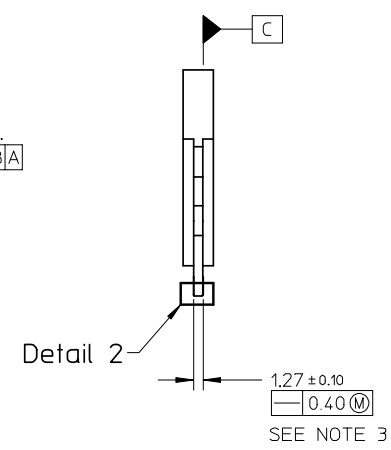
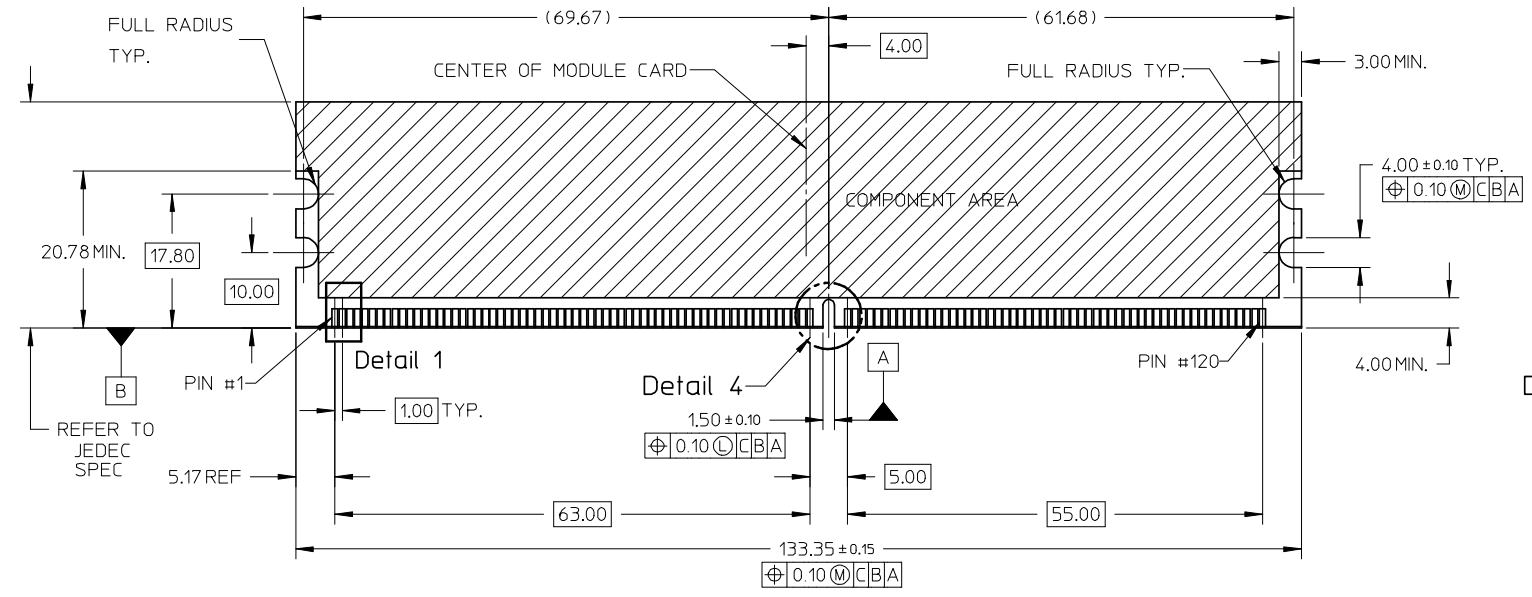
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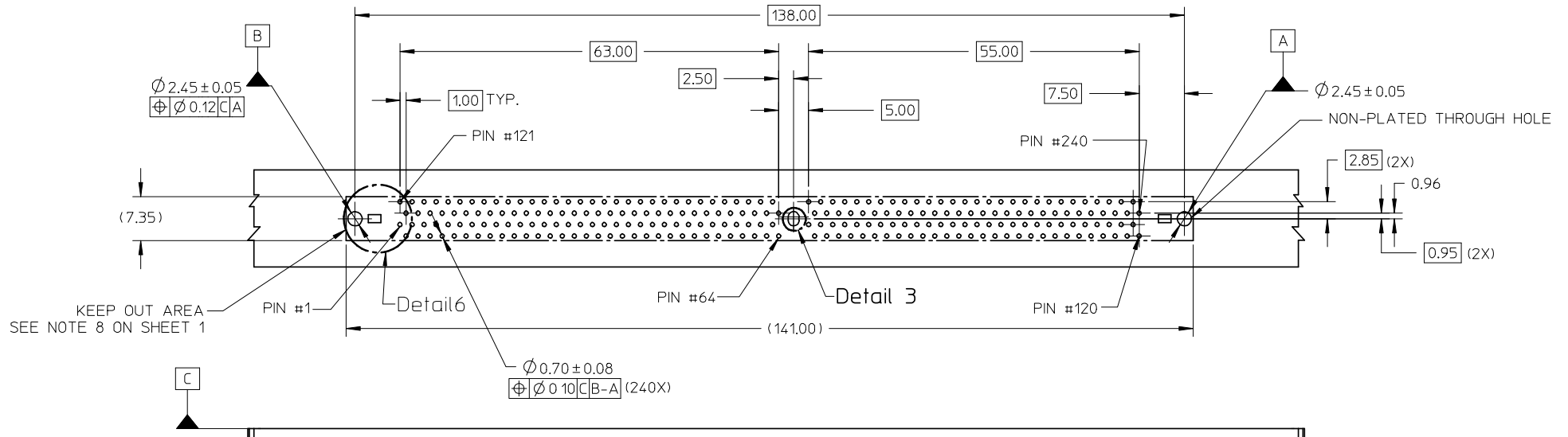
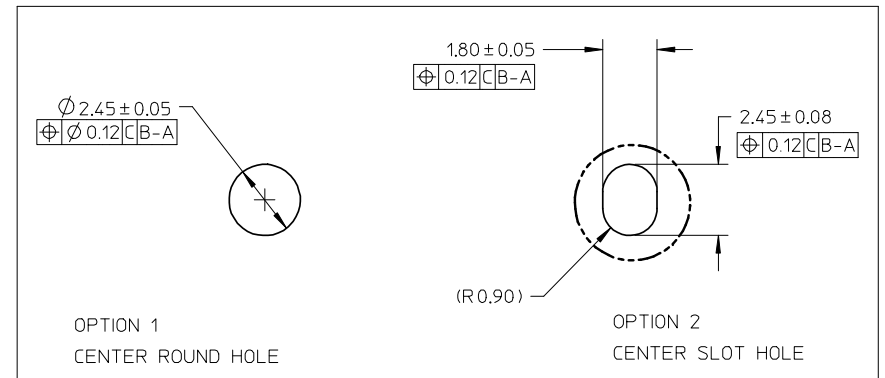
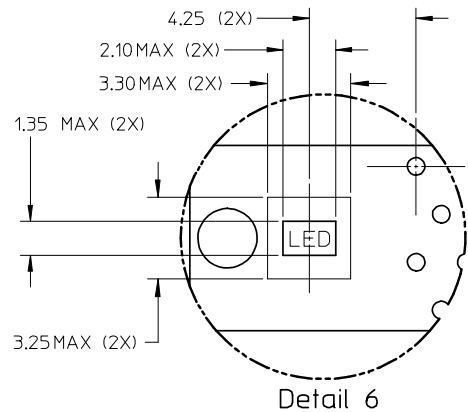
RECOMMENDED MODULE LAYOUT



NOTES:
1. MODULE CARD USED FOR TESTS ARE WITH 0.10MM CHAMFER.

ADD NOTE @SHT4 C1 EC NO: S2008-1044 DRWN:CMTE0 2008/05/15 CHKD:GTAN 2008/05/15 APPR:SHLENI 2008/05/15 REV D1			DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
				▽=0		mm	INCH	DRAWN BY CGOH	DATE 2002/05/09	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION) MOLEX INCORPORATED			
				◻=0	4 PLACES	± ---	± ---	CHECKED BY DSOH	DATE 2002/07/22				
					3 PLACES	± ---	± ---	APPROVED BY SKTOH	DATE 2002/07/23				
					2 PLACES	± 0.20	± ---	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-87705-001		SHEET NO. 3 OF 6	
					1 PLACE	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
					ANGULAR ± 5 °								

9 8 7 6 5 4 3 2 1



ADD NOTE @SHT4 C1 EC NO: S2008-1044 DRWN:CMTEO CHKD:CGTAN APPR:SHLEN 2008/05/15 2008/05/15 2008/05/15	QUALITY SYMBOLS ▽=0 ◊=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table><tr><td></td><td>mm</td><td>INCH</td></tr><tr><td>4 PLACES</td><td>± ---</td><td>± ---</td></tr><tr><td>3 PLACES</td><td>± ---</td><td>± ---</td></tr><tr><td>2 PLACES</td><td>± 0.20</td><td>± ---</td></tr><tr><td>1 PLACE</td><td>± ---</td><td>± ---</td></tr><tr><td colspan="3">ANGULAR ± 5 °</td></tr></table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.20	± ---	1 PLACE	± ---	± ---	ANGULAR ± 5 °			DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
				mm	INCH																				
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DESCRIPTION D1	DRAWN BY CGOH	DATE 2002/05/09	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS (FORKLOCK VERSION)																						
	CHECKED BY DSOH	DATE 2002/07/22																							
	APPROVED BY SKTOH	DATE 2002/07/23	 MOLEX INCORPORATED																						
	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-87705-001	SHEET NO. 4 OF 6																						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																							

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOR
87705-0021	CENTER (1.8V)	2.67	1.57	0.38uM / 15 uIN MIN. GOLD ON CONTACT, 2.54uM/ 100uIN MIN. TIN ON SOLDERTAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE	NATURAL
87705-1021		3.18	2.36		
87705-1053		3.66			
87705-0031		2.67	1.57	0.03uM / 1 uIN MIN. GOLD ON CONTACT, 2.54uM/ 100uIN MIN. TIN ON SOLDERTAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE	
87705-1031		3.18	2.36		
87705-0051		2.67	1.57	0.76uM / 30 uIN MIN. GOLD ON CONTACT, 2.54uM/ 100uIN MIN. TIN ON SOLDERTAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE	
87705-1051		3.18	2.36		

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			3 PLACES	± ---	± ---	DSOH	2002/07/22	MOLEX INCORPORATED			
			2 PLACES	± 0.20	± ---	APPROVED BY	DATE				
			1 PLACE	± ---	± ---	SKTOH	2002/07/23	MATERIAL NO.		DOCUMENT NO.	
D1	REV		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-87705-001		5 OF 6		
					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

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